

Specification of Thermoelectric Module

TEFC1-06612P

Description

The 66 couples, 13 mm × 12/13 mm size porch type single stage module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100/200 °C requirement. It has higher cooling efficiency than normal type module. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

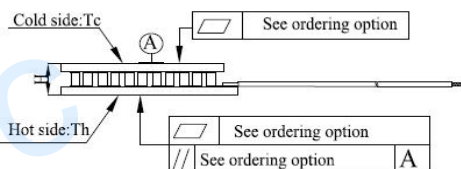
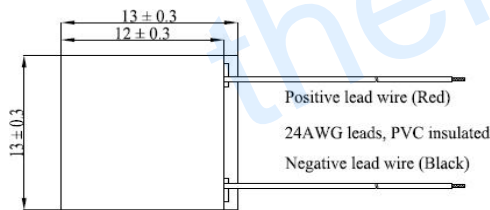
Application

- CCD Sensor
- Laser cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
ΔT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	8.7	9.4	Voltage applied to the module at DT _{max}
I _{max} (amps)	1.5	1.5	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	8.1	8.8	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	4.37	4.71	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 2.7±0.1	0: 0.015/0.015	60 ± 1/Specify
TF	1: 2.7±0.05	1: 0.01/0.01	60 ± 1/Specify
TF	2: 2.7±0.025	2: 0.008/0.008	60 ± 1/Specify

Eg. TF01: Thickness 2.7±0.1(mm) and Flatness 0.01/0.01(mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuSn (T_{melt} = 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

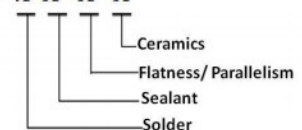
1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metallized)
2. Metallized (Au plating)

Naming for the Module

TEFC1-06612P-X-X-X-X



TEFC1-06612P-T100-NS-TF01-AIO

T100: BiSn (T_{melt}=138°C)

NS: No sealing

AIO: Alumina, white 96%

TF01: Thickness ± 0.1(mm) and Flatness/ Parallelism 0.01/0.01 (mm)

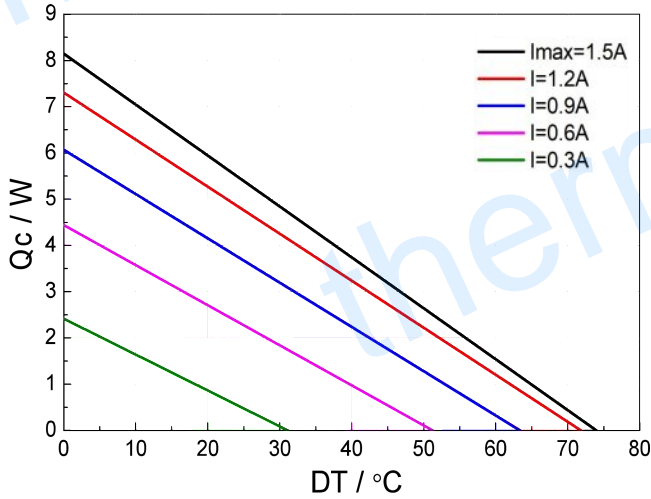
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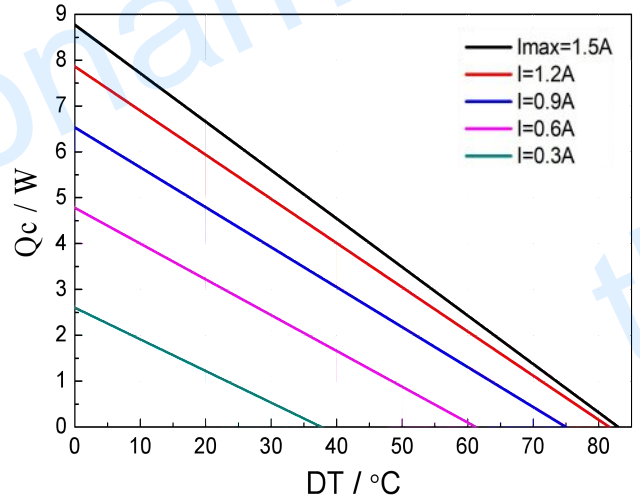
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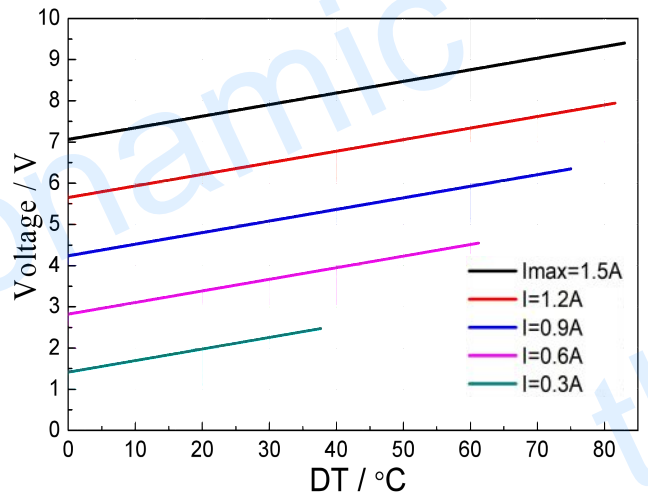
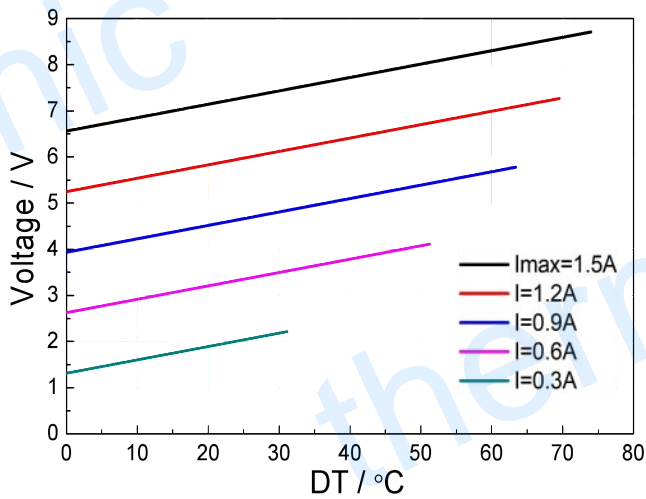
Performance Curves at Th=27°C



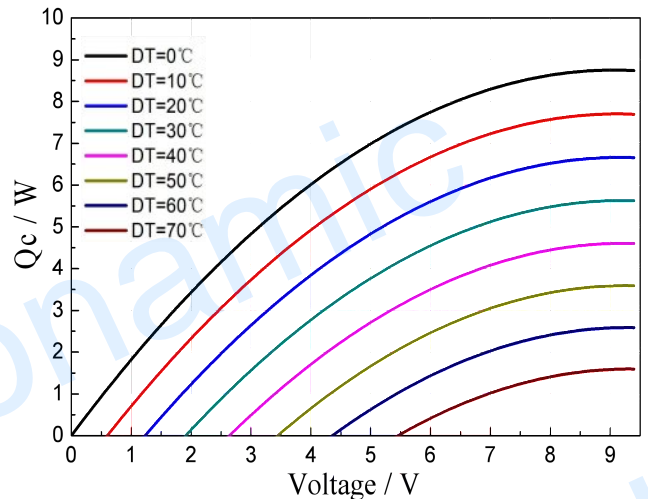
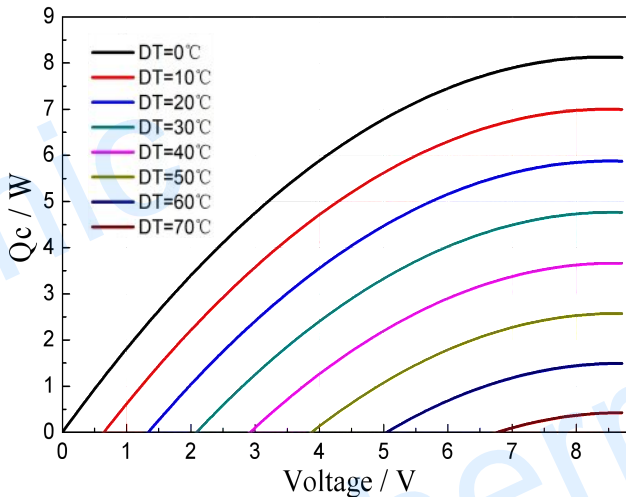
Performance Curves at Th=50°C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$



Standard Performance Graph $Q_c = f(V)$

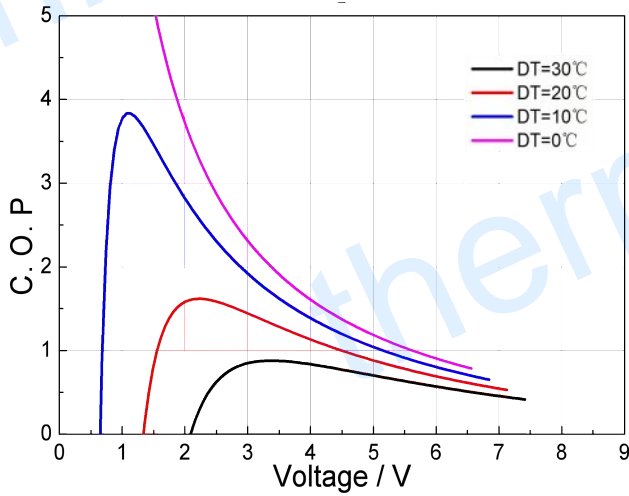
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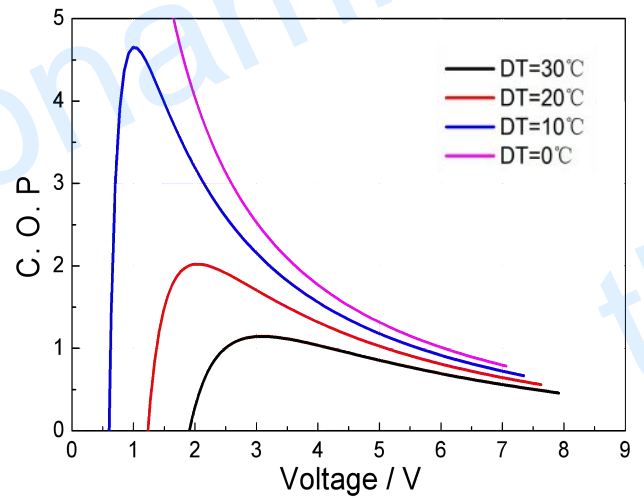
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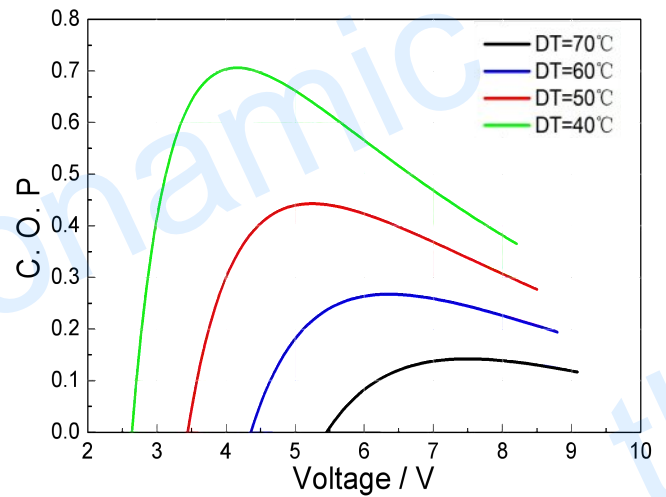
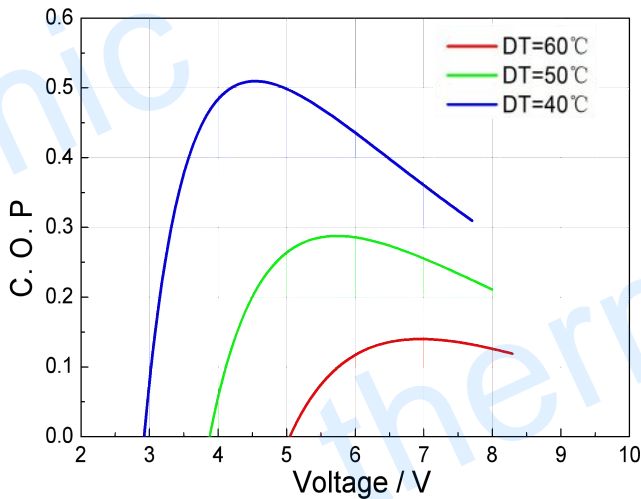
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.